



**PRODUCT INFORMATION**

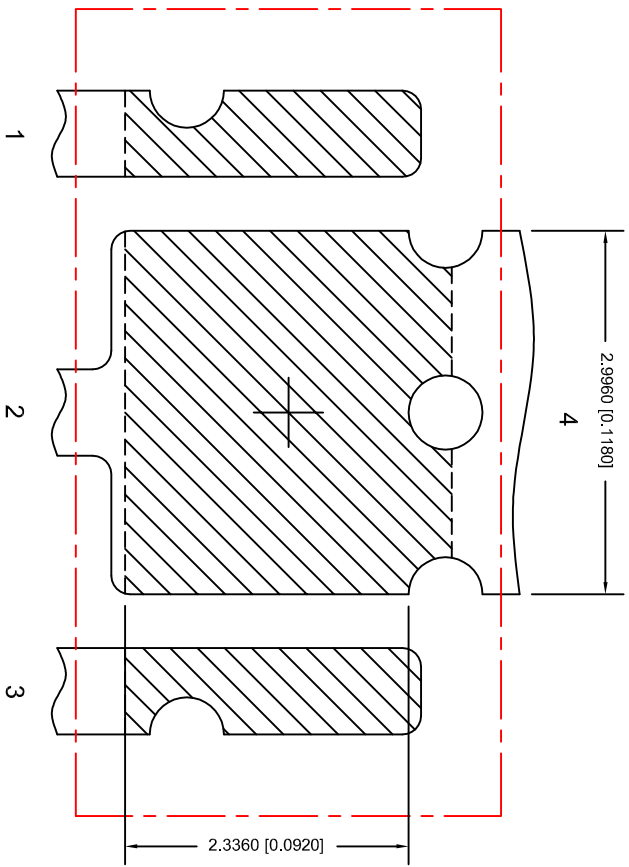
Customer :	
Device :	Device ID :
Die Size :	Wafer Material :
Package Type:	No. of Wires :
<b>SOT223</b>	

**MATERIAL INFORMATION**

Leadframe :	Pad Size :
<b>KFC with Ag spot plating</b>	<b>118 x 92 mils</b>
Epoxy :	Wire type :
Molding Compound :	Lead Finish :

**MARKING INSTRUCTION**

TOP :	BOTTOM :
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**BONDING DIAGRAM NO.**

**REF. BONDING DIAGRAM NO.**

SCALE  
not to scale

DRAWN BY: \_\_\_\_\_ REVIEWED BY : \_\_\_\_\_

REVISION NO.		APPROVALS		
REV. #	DESCRIPTION	PCN #	DEPT	DATE

SPECIAL INSTRUCTIONS :

Note : Dimension in mm [inches].